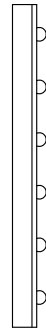
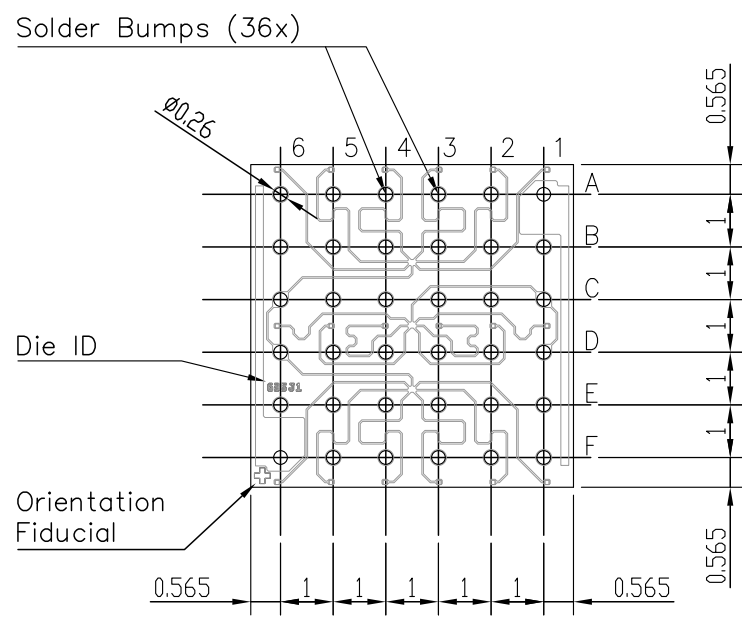


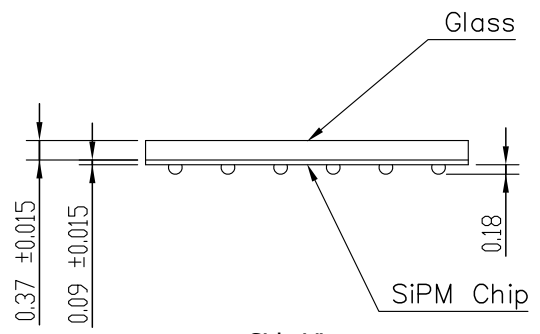
Top View
Scale 10:1



Side View
Scale 10:1



Bottom View
Scale 10:1

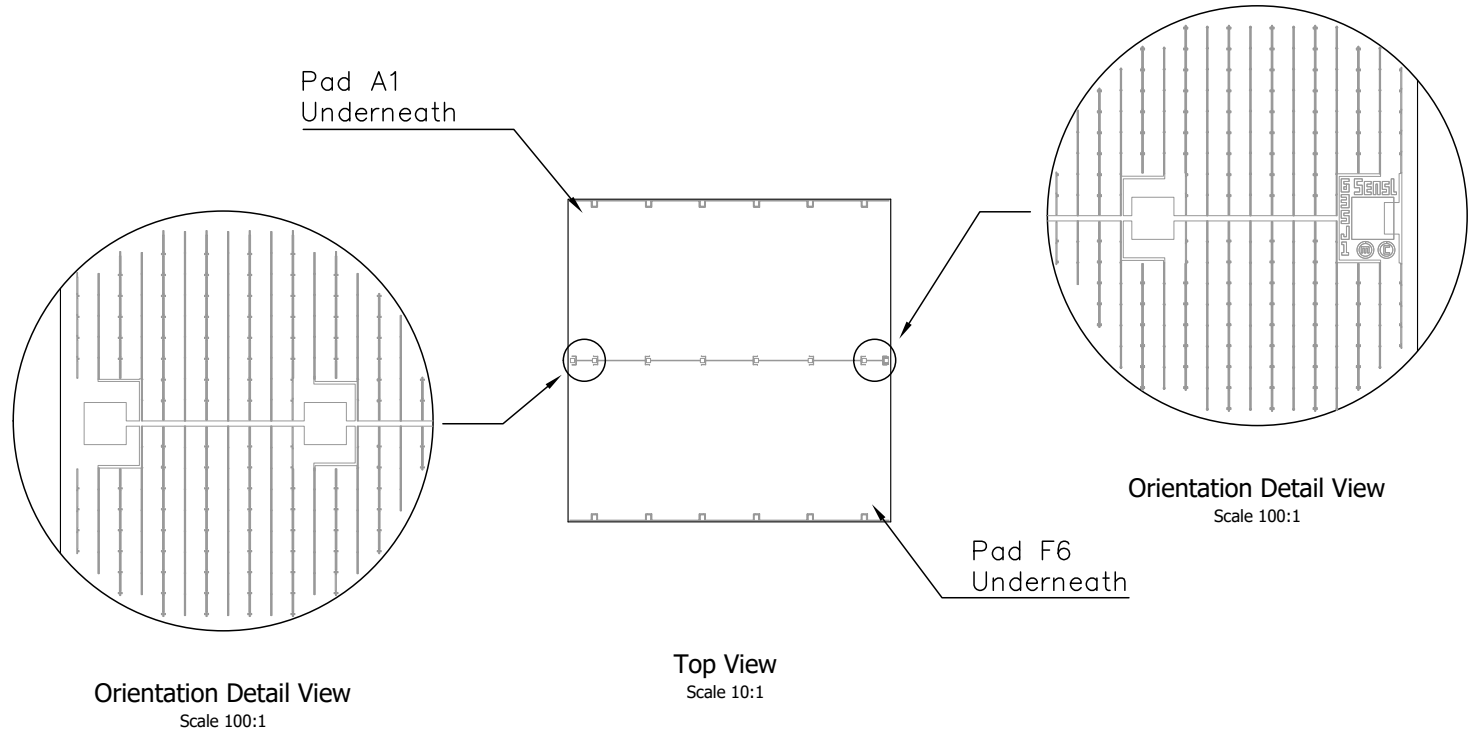


Side View
Scale 10:1

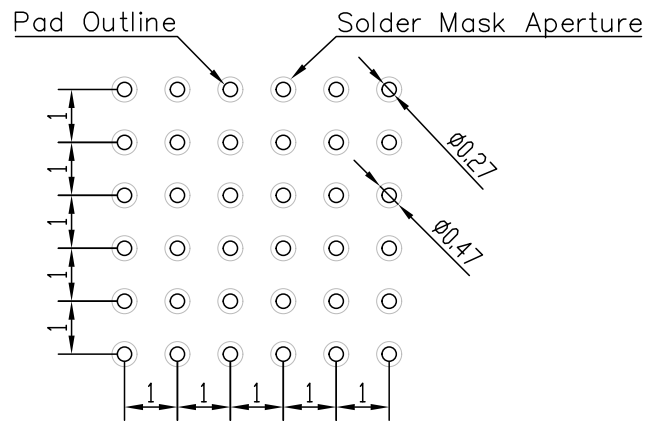
DATE	28 June 2017	REVISION	B	SCALE:	10 : 1
SensL Technologies Ltd				Sheet 1 of 5	
www.sensl.com					
DWG. NO:	SND0187	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE: MicroFJ-60035-TSV-A2					
PROJECTION:					

Pin Assignments

Pin#	Function
A1	Cathode
A2	NC
A3	NC
A4	NC
A5	NC
A6	NC
B1	NC
B2	NC
B3	NC
B4	NC
B5	NC
B6	NC
C1	Anode
C2	NC
C3	NC
C4	NC
C5	NC
C6	Fast Output
D1	Anode
D2	NC
D3	NC
D4	NC
D5	NC
D6	Fast Output
E1	NC
E2	NC
E3	NC
E4	NC
E5	NC
E6	NC
F1	NC
F2	NC
F3	NC
F4	NC
F5	NC
F6	Cathode



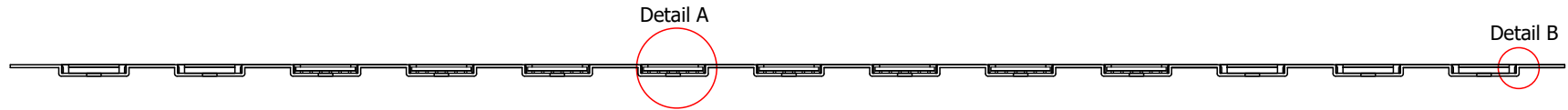
DATE	28 June 2017	REVISION	B	SCALE:	10 : 1
SensL Technologies Ltd					Sheet
www.sensl.com					2 of 5
DWG. NO:	SND0187	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFJ-60035-TSV-A2					
PROJECTION:					



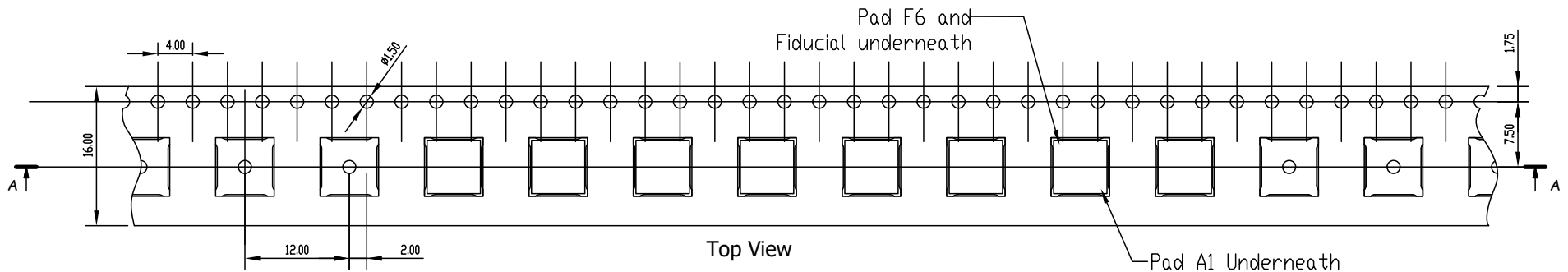
Recommended PCB Solder Footprint
Scale 10:1

NOTE: The No Connect (NC) pins are electrically isolated and should be soldered to a ground (or bias) plane to help with heat dissipation.

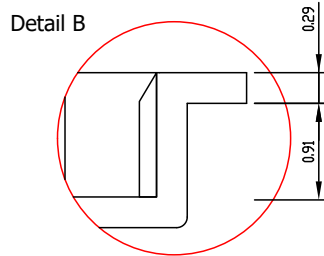
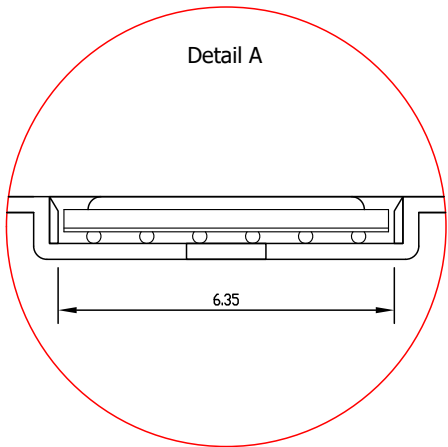
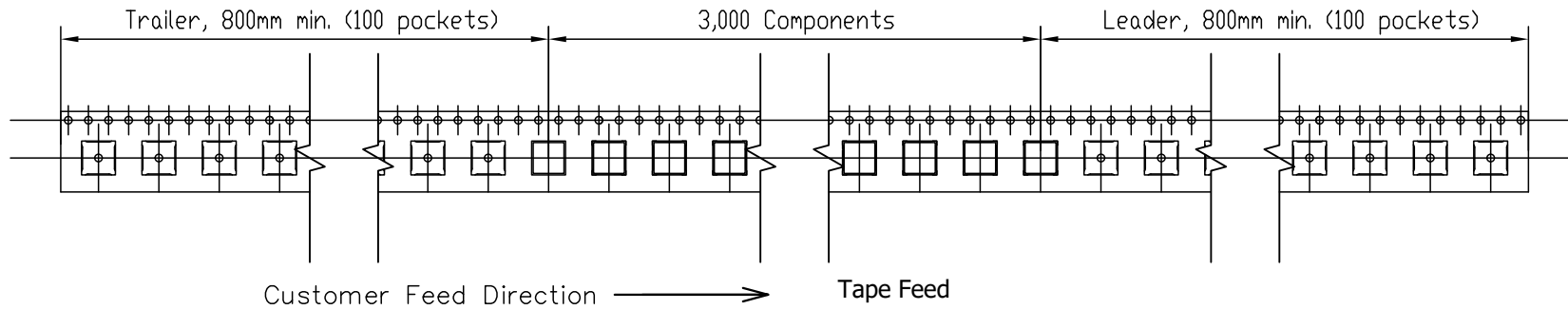
DATE	28 June 2017	REVISION	B	SCALE:	10 : 1
SensL Technologies Ltd				Sheet 3 of 5	
www.sensl.com					
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TITLE:					
MicroFJ-60035-TSV-A2					
PROJECTION:					



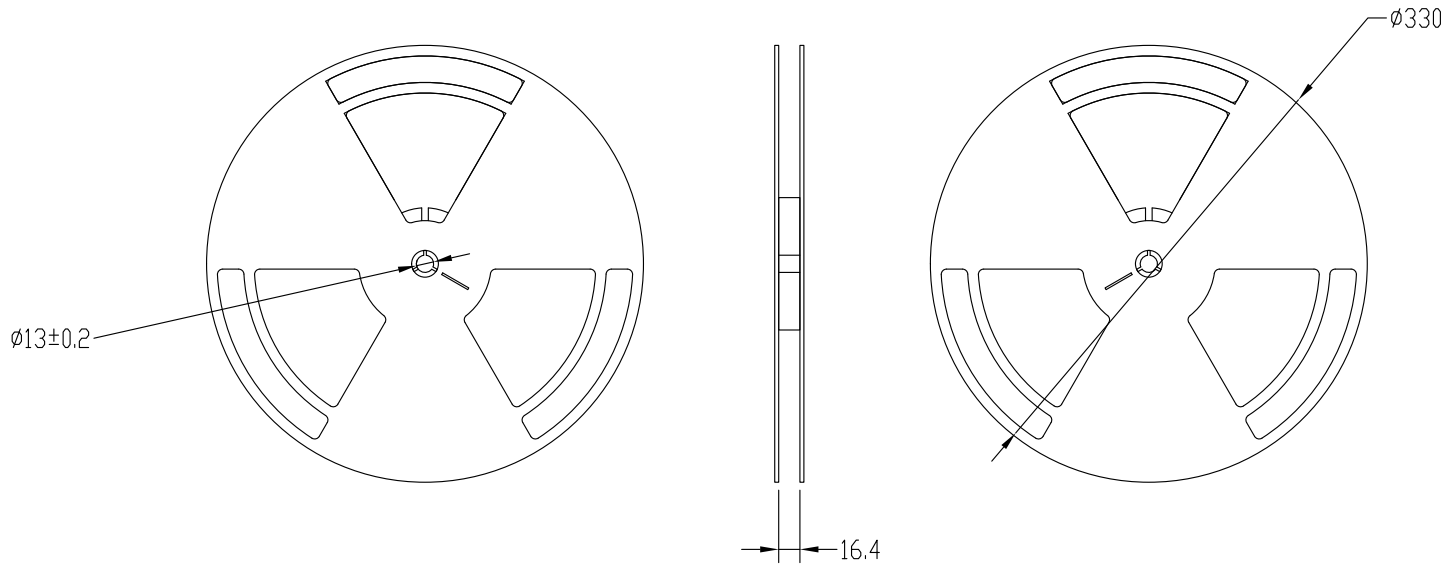
Section A-A



Top View

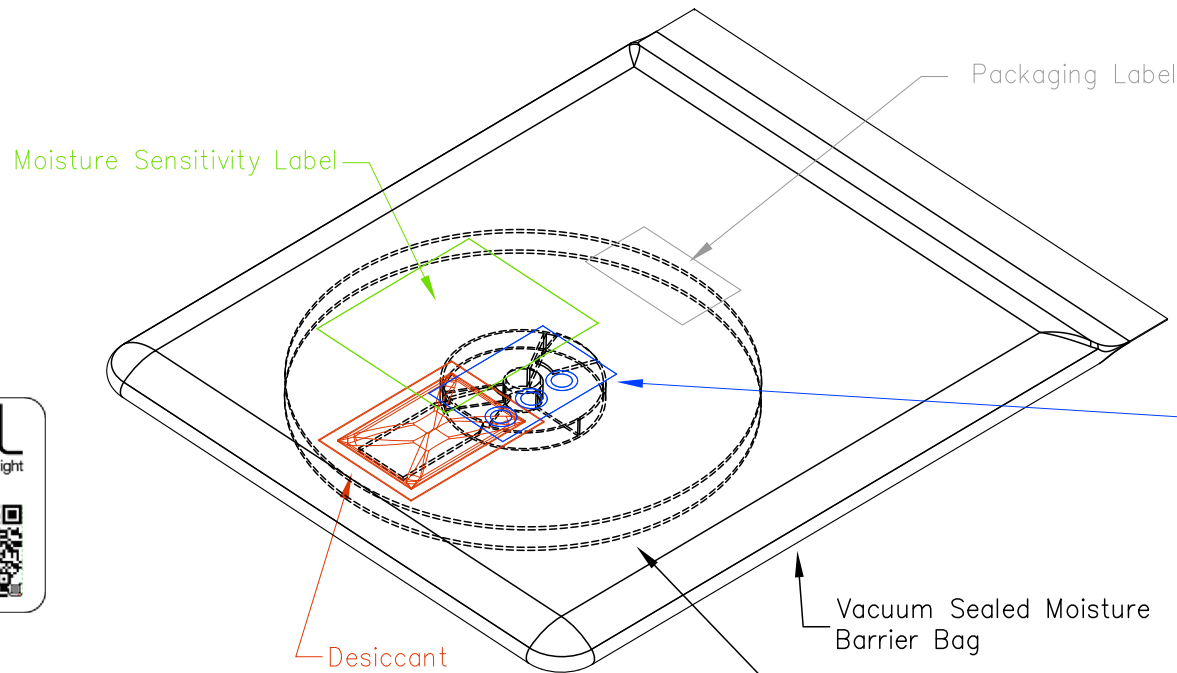


DATE	28 June 2017	REVISION	B	SCALE	10 : 1
SensL Technologies Ltd					Sheet
www.sensl.com					4 of 5
DWG. NO:	SND0187	DO NOT SCALE ALL DIMENSIONS IN MM			
TITLE:					
MicroFJ-60035-TSV-A2					
PROJECTION:					



	CAUTION	3
MOISTURE SENSITIVE DEVICES		
1. Calculated shelf life in sealed bag: 24 months at <math>< 40^{\circ}\text{C}</math> and <math>< 60\%</math> relative humidity (RH)		
2. Peak package body temperature: <u>260</u> °C if blank, see adjacent bar code label		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be		
a) Mounted within: <u>168</u> hours of factory conditions <math>< 30^{\circ}\text{C}</math> 60% RH, or		
b) Stored per J-STD-033		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at $23 \pm 5^{\circ}\text{C}$		
b) 3a or 3b are not met		
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: <u>20 Mar. 2014</u> if blank, see adjacent bar code label		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		

Details of Moisture Sensitivity Label



5% LEVEL 2A - 5A PARTS Bake parts if 10% IS NOT BROWN and 9% IS AZURE	10% LEVEL 2 PARTS Bake parts if 60% IS NOT BROWN	60% LEVEL 2 PARTS Bake parts if 60% IS NOT BROWN
BROWN-DRY AZURE-WET COBALT FREE HUMIDITY INDICATOR COMPLIES WITH IPC/JEDEC J-STD-033B		
<small>Failure Mode: DO NOT put this card into a bag if color has changed</small>		

Humidity Indicator Card

Humidity Indicator Card

sensl sense light
Part#: MicroFJ-60035-TSV
Revision: A2
Lot#: E4052
Quantity: 3000

Sample Packaging Label

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SensL Technologies Ltd					Sheet
www.sensl.com					5 of 5
DWG. NO:	SND0187	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFJ-60035-TSV-A2					
PROJECTION:		sensl sense light			